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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/614,928	07/08/2003	Jin-Yuan Lee	MEG00-009B	9220	
75	90 09/11/2006		EXAMI	INER	
George O. Saile			MENZ, DO	MENZ, DOUGLAS M	
28 Davis Avenu Poughkeepsie, 1	•	12603		PAPER NUMBER	
<i>5</i> • F • 7			2891		
			DATE MAILED: 09/11/2006		

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/614,928	LEE				
Office Action Summary	Examiner	Art Unit				
	Douglas M. Menz	2891				
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply						
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING D/ - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period v - Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tim will apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	l. ely filed the mailing date of this communication. O (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 15 Ju	<u>ıne 2006</u> .					
2a) This action is FINAL . 2b) ⊠ This						
	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims						
4) Claim(s) 25-29,31-35 and 45 is/are pending in 4a) Of the above claim(s) is/are withdray 5) Claim(s) is/are allowed. 6) Claim(s) 25-29,31-35 and 45 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/o	wn from consideration.					
Application Papers						
9) The specification is objected to by the Examine 10) The drawing(s) filed on <u>08 July 2003</u> is/are: a) Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Example 11.	\boxtimes accepted or b) \square objected to be drawing(s) be held in abeyance. See ion is required if the drawing(s) is obj	ected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 						
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	te				

U.S. Patent and Trademark Office PTOL-326 (Rev. 08-06)

DETAILED ACTION

Declaration

The declaration filed on 6/15/06 under 37 CFR 1.131 is sufficient to overcome the Taniguchi reference.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 25-29,31-35 and 45 are rejected under 35 U.S.C. 102(b) as being anticipated by Tokuda et al. (US 5870289).

Regarding claim 25, Tokuda discloses an electronic package comprising:

- a first circuitry component having a top surface (210-n, Fig. 4);
- a second circuitry component (210-n-1, Fig. 4) over said top surface;
- a first insulating layer (220-n-1, Fig. 4) covering said second circuitry component and said top surface; and a metal layer (wiring layer on top 220) on said insulation layer (Fig. 4 and Cols. 15-16).

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Regarding claim 26, Tokuda further discloses wherein said first circuitry component comprises a semiconductor chip (210, Fig. 4).

Regarding claim 27, Tokuda further discloses wherein said second circuitry component comprises a semiconductor chip (210-n-1, Fig. 4).

Regarding claim 28, Tokuda further discloses a bump between said first and second circuitry components (Fig. 4 and Cols. 15-16).

Regarding claim 29, Tokuda further a second insulating layer (230, Fig. 4) between said first and second circuitry components and enclosing said bump (Fig. 4 and Cols. 15-16).

Regarding claim 31, Tokuda further discloses a via (270, Fig. 4) through said first insulation layer and connecting said first circuitry component and said metal layer (Fig. 4 and Cols. 15-16).

Regarding claim 32, Tokuda further discloses wherein said first insulation layer (220-n-1, Fig. 4) has a top surface comprising a first region and a second region, said first region being over said second circuitry component, said second region being not

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over said second circuitry component, wherein said first and second regions are coplanar (Fig. 4 and Cols. 15-16).

Regarding claim 33, Tokuda further discloses wherein said metal layer is on said first and second regions (Fig. 4 and Cols. 15-16).

Regarding claim 34, Tokuda further discloses a bump over said metal layer (Fig. 4 and Cols. 15-16).

Regarding claim 35, Tokuda further discloses wherein said second circuitry component comprising a top surface and a bottom surface facing said top surface of said first circuitry component, said first insulation layer over said top surface of said second circuitry component (Fig. 4 and Cols. 15-16).

Regarding claim 45, Tokuda further discloses a substrate (280, Fig. 4) and a second bump (290) connected to a bottom surface of the substrate, wherein the first bump is connected to a top surface of the substrate (Fig. 4 and Cols. 15-16).

Response to Arguments

Applicant's arguments with respect to claims 25-35 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Douglas M. Menz whose telephone number is 571-272-1877. The examiner can normally be reached on M-F 8-5.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on 571-272-1722. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.